

METHOD OF MANUFACTURING ELECTRONIC CARDS

Field of the invention

The present invention concerns a method of manufacturing complex electronic cards each including a first electronic unit, at least partially
5 arranged in a window in a solid layer of the card, and a second electronic unit electrically connected to the first electronic unit and incorporated in an internal layer formed by a filler material which covers at least one of the surfaces of said second electronic unit. In particular, the filler material is a resin, provided in a non solid state during the manufacturing process or a
10 resin provided in the form of at least partially melted hot melt sheets, so as form an internal layer of the card. It will be noted that the internal layer formed by the filler material can contain other solid structures or elements, in particular positioning or filler structures for said internal layer.

"Electronic card" means a bank type card and also other devices in
15 various forms, particularly an electronic tag or a portable electronic device.

Background of the invention

A method is already known from EP Patent No. 1,559,068 for manufacturing electronic modules which each include two insulating sheets
20 defining the external faces thereof, at least one electronic element having an external surface that substantially touches one of the external surfaces of the electronic module and an electronic circuit arranged between the two insulating sheets and connected to the electronic element. This method provides the following steps:

25 - providing at least a first insulating sheet including a window for housing the electronic element;

- inserting the electronic instrument in the window of the first insulating sheet, said electronic element being provided with conductive connection pads arranged on an inner surface opposite to the external surface thereof;

5 - superposing an adhesive protective film that extends at least into the area between the electronic element and the edges of the window, the protective film holding the electronic element in the window and closing any slit between said electronic element and the lateral wall of said window;

 - placing the electronic circuit in a zone close to the window and
10 connecting the electronic element to the electronic circuit through a window provided or made in the protective film and located opposite said conductive connection paths;

 - depositing a filler material on the set of elements already provided and superposing a second insulating sheet on the filler material;

15 - pressing or laminating the assembly produced by the preceding steps, the filler material forming a layer compensating for any surface contours resulting from assembling the electronic module.

The manufacturing method described above solves an important problem, namely, preventing the filler material, generally formed by a resin
20 which is in a viscous liquid state when pressure is applied to form the electronic module, from flowing into any slit between the electronic element and the lateral wall of the window in which it is arranged, so as to prevent the resin extending at least partially onto the visible external surface of the electronic element. However, the manufacturing method presents a problem
25 in relation to the sequence of steps, in particular the fact that the electrical connection between the visible electronic element and the internal electronic unit is achieved once the electronic element has been inserted in a window in an external insulating layer of the card being manufactured and the adhesive protective layer is in place. This sequence of steps raises a
30 practical problem given that card manufacturing equipments or facilities are not generally equipped with a device for welding or assembling various

electronic units. Indeed, generally, the various electronic circuits and elements are first assembled to form electronic devices and then these electronic devices are taken to a conventional card manufacturing equipment or facility in which the various materials used to form the cards
5 are provided and processed in an appropriate manner to obtain high quality electronic cards into which the electronic devices are respectively incorporated. The aforecited Patent of the prior art does not propose temporally separating production of the electronic devices from the manufacture of the cards incorporating these electronic devices. Although
10 the method described in the aforecited document can be implemented and used to obtain complex electronic cards, it has a major drawback for those skilled in the art specialised in manufacturing finished electronic cards or inlets, who prefer to separate the production of the electronic devices from the card forming process.

15 It is an object of the present invention to overcome the major drawback of the prior art method mentioned above.

Summary of the invention

The electronic card manufacturing method according to the invention
20 is mainly characterized in that the electronic assembly or device, formed by at least a first electronic unit provided in a window in a solid layer of the card and by a second electronic unit arranged in an inner layer or the body of said card, is manufactured first, prior to production of the electronic cards; i.e. before the solid layers and other materials forming the body of the card
25 are added. Thus, the electronic device incorporated into each card is made in a preliminary step, in accordance with a conventional process. In order to do this, various ways of implementing the card manufacturing method are proposed. In particular, according to the invention the protective film is formed of several parts or a single part with at least one slit.

If the protective film is in several parts, these parts have complementary profiles that can cover the external edge of a rear face of the first electronic unit, while extending into the entire peripheral zone of said first electronic unit and defining a window allowing the electrical connection between the first and second electronic units to pass through. This window thus has smaller dimensions than those of the first electronic unit. Thus, once the electronic device has been taken to the card manufacturing equipment or facility and the first electronic unit has been at least partially inserted into a window in the first solid layer, the protective film can properly cover any slit between the lateral wall of the window and the first electronic unit.

If the protective film is formed of a single part with at least one slit, this slit is either a through slit between a central window in the film and the outer edge thereof, said slit thus being able to be moved aside to allow the electrical connection to pass inside said central window, or, when the slit is not a through slit, it is arranged such that the first or second electronic unit can pass through the central window in the protective film by moving aside the parts of said protective film located at the edge of said window.

The electronic card manufacturing method according to the invention includes three main implementation modes. In a first implementation mode of the invention, as described in claim 1 annexed to this description of the invention, the electronic device, formed of at least first and second pre-assembled electronic units, is first of all brought to the card manufacturing equipment or facility where the first electronic unit is placed in a window in a first solid layer. Next, a protective film of the type described above is provided and arranged so as to cover essentially any slits that may exist between the first electronic unit and the lateral wall of the window.

According to the second implementation mode defined in claim 2 annexed to this description of the invention, the electronic assembly or device is first of all made and then, before the electronic device is provided on a first solid layer and the first electronic unit is arranged in the window in

said solid layer, the protective film is assembled to said electronic device so that the electrical connection is located in a window defined by the protective film and so that the latter is thus located between the first and second electronic units. Next, the pre-assembled electronic device and protective film are taken to the card manufacturing equipment or facility where said solid layer is provided, the first electronic unit is conveniently inserted in the aperture provided in the solid layer, and the protective film is applied across a zone peripheral to the window and, if this has not been previously done, at least against the lateral surface and/or the outer edge of a rear face of the first unit. In a variant of this second embodiment, a protective film is first of all assembled to said first unit by applying said film at least against the outer edge of a rear face of said first unit, then an electrical connection is established with the second electronic unit through an aperture in said film before the protective film pre-assembled with the electronic device is taken to a card manufacturing equipment or facility where the first solid layer is added.

According to the third implementation mode of the invention, as defined in claim 6 annexed to this description of the invention, firstly the electronic assembly or device is manufactured, formed of at least the first and second electrically connected electronic units, and then a structure including a protective film having at least one window, which has smaller dimensions than those of the first electronic unit and has flaps at the periphery thereof, separated by slits, and a first solid layer having at least one window for at least partially receiving the first electronic unit. Said protective film is assembled to the first solid layer with said at least one aperture centred on said at least one window. Next, said structure and said electronic device are taken to a equipment or facility and the first electronic unit is placed opposite said aperture, then said first unit is pushed into said window by folding said flaps towards the lateral wall of the aperture until the flaps are released and then moved back up at least partially in the direction of the general plane of the protective film. Next, the first unit is moved back

up in the direction of said aperture and said flaps are at least partially applied against the lateral surface and/or a rear face of said first unit, so as to close any slits between the lateral wall of the window and the first unit, said electrical connection passing through said aperture.

5 Finally, in the method according to the invention a filler material is provided on the protective film, in particular a resin, which is at least partially in a non solid state when a layer or body of the cards is at least partially formed by the filler material, the latter at least partially covering said electrical connection of said electronic assembly or device.

10 It will be noted that, in a variant, the protective film has an adhesive surface that holds it in place and also, in a subsequent step of depositing a filler material at least partially covering the electronic connection, prevents said filler material from infiltrating underneath the protective film and thus flowing into the window. Other variants for holding the protective film in
15 place can be envisaged. For example, the solid layer may have an adhesive top surface in the area provided for the protective film. In another variant, the protective film is thermally welded to the solid layer, particularly in several specific areas.

 Various variants of the manufacturing method according to the
20 invention form the subject of the dependent claims.

Brief description of the drawings

 Other features and advantages of the electronic card manufacturing method according to the invention will also appear from the following
25 detailed description of implementation modes of this method, this description being made with reference to the annexed drawings, given by way of non-limiting example and in which:

- Figure 1 shows a first embodiment of the electronic device incorporated in each card manufactured in accordance with the method of the invention;

5 - Figure 2 shows the electronic assembly or device of Figure 1 assembled with a protective film;

- Figure 3 is a top view of an electronic card according to the invention in an intermediate state during the manufacturing method of the invention;

10 - Figure 4 is a cross-section along the line IV-IV of Figure 3 with the electronic card in a finished or semi-finished state;

- Figure 5 is a cross-sectional view along the line V-V of Figure 3 with the electronic card in a finished or semi-finished state;

- Figures 6A and 6B illustrate respectively two variants of a protective film according to the invention;

15 - Figure 7 shows schematically a second embodiment of an electronic device incorporated into each card manufactured in accordance with the method of the invention;

20 - Figure 8 is a cross-sectional view of a card obtained via the method according to the invention and incorporating the electronic device of Figure 7;

- Figure 9A shows schematically one step of a second implementation mode of the method according to the invention;

- Figure 9B partially shows the intermediate product resulting from the step shown in the diagram of Figure 9A;

25 - Figure 10 shows a cross-section of a variant of an electronic card obtained via the method according to the invention;

- Figure 11 is a top view of a protective film for producing a batch of cards in accordance with a third implementation mode of the method of the invention; and

30 - Figures 12A, 12B, 12C, 12D and 12E show a series of steps occurring in the aforementioned third implementation mode.

Detailed description of the invention

With reference to Figures 1 to 5, a first implementation mode of an electronic card manufacturing method according to the invention will be
5 described below.

In a preliminary step of this card manufacturing method, a first electronic unit 4 is assembled to a second electronic unit 10 to form electronic assembly or device 40. Electronic unit 10 is formed of a PCB type support 12 at the surface of which various components 14, 15 and 16 are
10 arranged. These electronic circuits can be formed of any type of component and may have various functions. Component 14 can for example be a micro-processor, component 15 a display and component 16 a battery. It will be noted that the second electronic unit 10 can also, in a variant, form a battery or, in another variant, form an antenna. It will also be noted that the
15 first electronic unit can be formed by a single external electric contact pad connected to an internal electronic unit of the card.

PCB 12 can be rigid or flexible. This support 12 is extended by a tongue 18 which is flexible, or at least capable of undergoing elastic deformation. Conductive paths 20 and 21 for establishing electrical
20 connections between unit 10 and unit 4 are arranged on tongue 18. For this purpose, unit 4 has electrical connection pads 22 to which end pads 20a and 21A of paths 20 and 21 are electrically connected, particularly by tin welding or using a conductive adhesive. The tin can be deposited beforehand in the form of a thin film at the surface of contact pads 22. It will
25 be noted that, according to the terminology used for this description of the invention, tongue 18 fitted with conductive paths forms an electrical connection between the first electronic unit 4 and the second electronic unit 10. It will be noted that the electrical connection described here is an advantageous example, but that any type of electrical connection between
30 two electronic units known to those skilled in the art can be envisaged. In

particular, more than two conductive paths or electrical connections can be provided between the two units. Tongue 18 can act as a support for a large number of electric connection paths between the two electronic units.

After electronic device 40 has been formed, a protective film in two
5 parts 24 and 26 is provided, the respective profiles of said parts defining, when assembled, a central aperture 32 into which electrical connection 18 passes, said aperture having smaller dimensions than those of first electronic unit 4. The two part protective film is arranged between the first and second electronic units 4 and 10, with electrical connection 18 passing
10 through aperture 32. In the variant shown, the two parts have a general U shape. In another variant, only one of the two parts is U-shaped or both parts are L-shaped. The protective film has a zone peripheral to aperture 32 which is applied against the outer edge 5 of the rear face of first electronic unit 4. Protective film 24, 26 then extends into a zone peripheral to first
15 unit 4 as shown in Figure 2. The function of the protective film will be described below.

Electronic devices 40 fitted with the protective film are then taken to an electronic card production equipment or facility where several cards or inlets are generally manufactured simultaneously in the form of a plate or
20 sheet. In the equipment or facility, a first solid layer is provided, said layer having at least one window 6 provided for each card and intended to receive at least partially the first unit 4 of electronic device 40. Each unit 4 is thus placed in a window 6 in solid layer 8. The protective film is then applied against the peripheral zone of window 6 so as to close any slit 28 between
25 the lateral wall 30 of said window and first unit 4. To ensure that slit 28 is entirely closed by the protective film, the two parts 24 and 26 thereof have a zone 34 where the parts are superposed, part 26 having a region that partially covers part 24. In a variant, it is, however, possible to omit the overlapping zone, but to assembly the two parts properly side by side
30 without leaving any space between them.

In a subsequent step, a filler material 42 is provided on first solid layer 8 and on the protective film, and pressure is for example applied to the filler material which is then in a non solid state, to form a layer of the electronic cards being manufactured, with the filler material surrounding
5 electrical connection 18.

In the variant shown in Figures 4 and 5, before pressure is applied to filler material 42, a second solid layer 44 is provided on said filler material. Preferably, the protective film includes an adhesive or heat-reactivable surface allowing said protective film to be fixed firstly to the rear face of
10 unit 4 and/or said protective film to be bonded to the top surface of solid layer 8. The fact that the protective film is in two or more parts means that it can easily be arranged at the edge of the rear face of electronic unit 4 while defining an aperture 32 that allows electrical connection 18 to pass through. Owing to this feature, it is thus possible to arrange the protective film
15 properly after electronic device 40 has been formed.

It will be noted that the electronic device can include more than two units, in particular at least two units at least partially arranged in respective windows in one or two solid layer(s) so as to be visible.

Figures 6A and 6B show two variants of another embodiment of the
20 protective film which also satisfies the objective of the present invention. Protective film 50 of Figure 6A is formed of a single part defining a central aperture 32 and having a slit 52 which passes through film 50 from aperture 32 as far as the external edge of said film. It is thus of the slit ring type. Again, so as to be able to arrange an area of film 50 peripheral to
25 aperture 32 against the outer edge of the rear face of unit 4, aperture 32 has smaller dimensions than those of unit 4. The electrical connection 18 can easily be arranged in aperture 32 by inserting connection 18 into slit 52, and then moving it until it is located in aperture 32. Next, film 50 is correctly placed against the rear face of unit 4 in a similar way to the arrangement
30 shown in Figures 2 and 4.

Protective film 54 of the variant shown in Figure 6B differs in that a plurality of slits 56a to 56d is arranged at the periphery of aperture 32. These slits do not pass through film 54 as far as the outer edge thereof. They can therefore define parts peripheral to aperture 32, which can easily
5 be folded outside the general plane of film 54 and thus allow an electronic unit, of larger dimensions than those of aperture 32, to pass through. To arrange protective film 54 between the first and second units 4 and 10 of an electronic device 40 in accordance with the present invention, unit 4 is pushed through aperture 32 moving aside the parts peripheral to said
10 aperture 32 located between slits 56a to 56d. These peripheral parts thus undergo elastic deformation and return into the general plane of protective film 54 once unit 4 has passed through. The electrical connection 18 is then in aperture 32. So as to limit as far as possible any flow of resin into any slit or generally of any filler material deposited when the card body is being
15 formed, the slits preferably have a minimum or zero width. "Slit" therefore means in particular making a simple cut in the protective film, particularly along a straight line portion.

The filler material provided to form the core of the card or an internal layer of said card is preferably formed by a resin deposited in viscous liquid
20 state or in the form of a hot melt solid which is then at least partially melted so as to coat second electronic unit 10. According to a preferred implementation of the step of forming the core or internal layer of the card, firstly the second units 10 are rotated by elastically folding electrical connection 18, units 10 then being turned onto their top side on the other
25 side of aperture 6 relative to the side provided for these units in the centre of the finished card. In a variant, units 10 are simply raised by suitable means and placed for example momentarily in a substantially vertical position. Next, a first part of the filler material is placed on bottom solid sheet 8, so that this first resin part at least partly covers the areas of said
30 layer 8 where units 10 will eventually be arranged. Then, electronic units 10 are folded down or rotated again onto the bottom side thereof and placed

on the first part of the filler material deposited beforehand. A second part of the filler material is then placed on units 10 so that the filler material completely coats the units and most of electrical connection 18. This method ensures that the filler material is present underneath
5 components 14 to 16 of unit 10. This thus avoids some parts of bottom layer 8 not being coated with resin; which could then cause subsequent surface deformation problems for the finished card.

According to an alternative implementation of the method of the invention, in particular in the situation described with reference to Figures 1
10 to 5, the resin is essentially provided during a single same step and then spread out by using a roller or blade in one direction which ensures that part of the resin thereby spread out penetrates beneath support 12 of unit 10. This is made easier because the electronic components of unit 10 are located underneath said support. Thus, support 12 is initially located at
15 some distance from solid layer 8 and a resin in a viscous liquid state easily penetrates beneath and also partly above said support during the step of forming a resin layer. It will be noted here that, in a variant where the electronic device 40 is manufactured so that the components of the second unit 10 are located above support 12 once the first unit 4 has been arranged
20 in the aperture of the bottom layer, means can be provided to assist the flow of part of the resin underneath support 12. By way of non-limiting example, this support can have small projecting portions thus creating an empty space between said support and the bottom solid layer. Apertures can also be provided in support 12 to encourage the flow of part of the resin
25 underneath said support. In a variant, support 12 can have a raised end part, particularly defining an inclined plane. The resin is then spread out by a roller or a blade in a direction that tends to lift the second internal electronic units, the horizontally pushed resin pressing against these raised parts relative to the general plane of support 12 and thus exerting an
30 upward thrust. In a variant, the resin is introduced laterally between the two solid layers 8 and 44, particularly by injection into a mould.

According to another alternative implementation of the method according to the invention, in the aforementioned case where support 12 of the second electronic unit 10A is provided underneath the electronic components of the second unit, a resin film 60 is deposited beforehand
5 underneath support 12. This resin film may be similar in nature to a resin film 62 deposited underneath protective film 50 (Figure 7).

According to the embodiment of the electronic device 40A of Figure 7, the electrical connection 64 between units 4a and 10A is formed by metal
10 tongues which come out of module 14A. These metal tongues can be deformed and allow protective film 50 to be easily arranged against the rear face of unit 4A. It will be noted that unit 4A has a lateral wall with a recess. As shown in Figure 8, electronic device 40A is then arranged on a solid layer 8A having apertures 6A with steps against which the top part of unit 4A rests. Solid layer 8A can be formed of two layers laminated to each
15 other and each having an aperture of different dimensions to define a housing having a cross-sectional profile matching that of unit 4A. In the embodiment of a card according to the invention shown in Figure 8, two transparent external films 66 and 68 are finally added. It will be noted that transparent film 66 covers electronic unit 4A. The latter forms, for example,
20 a light sensor, a solar sensor, or a light emission source, in particular within the infra-red range. Unit 4A can also define an electronic display visible through transparent film 66.

It will also be noted that resin film 60 located between layer 8A and support 12 can be identical to resin 42 forming the internal layer of the card.
25 Adhesive film 60 can be made to adhere to the bottom layer by applying heat through said layer.

With reference to Figures 9A, 9B and 10 a second implementation mode of the card manufacturing method according to the present invention will now be described. This essential difference between this second
30 implementation mode and the first mode is a variation in the sequence of steps of the method. As shown schematically in Figure 9A, electronic

assembly or device 40B is firstly provided on bottom solid layer 8 and unit 4B is inserted into cavity 6 provided in said layer. It will be noted here that one part 42A of the resin, intended to form an internal layer in which electronic unit 10B is incorporated, is provided before device 40B or, in a variant, this resin part 42A is added while unit 10B is raised or turned over, as was described previously. Once the first unit 4B is partially housed inside aperture 6 of solid layer 8, protective film 50 is provided and set in place as shown in Figure 9B, by inserting the electrical connection 64A in aperture 32 of film 50, through slit 52 provided in said film (Figure 6A). It will be noted that unit 4B can be secured to the layer by dots of adhesive before the protective film is arranged. This film is formed in this variant of a single part having at least one slit starting from an aperture made in said part, the dimensions of said aperture being smaller than those of first unit 4B. Protective film 50 is set in place so that it covers a peripheral zone of window 6 and the outer edge of the rear face of first unit 4B where electrical connection pads 22 are arranged. This arrangement according to the invention allows any slit between the lateral wall of each window provided in solid layer 8 and the first unit 4B placed in said window to be closed. As in the first implementation, the protective film can be formed of several parts with respective profiles which, when assembled on the bottom solid layer 8, define an aperture into which the electrical connection 64A passes.

Then, as in the first implementation mode of the invention, a filler material, particularly a resin, is deposited on the first solid layer 8 and protective film 50, and the filler material is spread out in a non solid state to form a layer of the electronic cards, said filler material then covering the second electronic unit 10B.

The card variant shown in Figure 10 differs in particular from that of Figure 8 in that the bottom transparent film 70 has a window 72 arranged opposite the external surface of the first unit 4B. Electronic unit 4B here forms for example a fingerprint sensor. This latter variant has the advantage

of closing any slit between unit 4B and the lateral wall of window 6 on the side of the external surface of solid layer 8.

It will be noted that, in the various card embodiments described above, the dimensions of the protective film are limited such that it does not
5 extend underneath the whole of the second electronic unit incorporated in the resin layer. In particular, the protective film has reduced dimensions and is not superposed on the second internal unit incorporated in the resin layer. This thus avoids having a film covering most of the bottom solid layer and thus forming an interface between the resin layer and the bottom solid layer.
10 Even if the protective film has adhesive or heat-reactivable surfaces, the adherence of the film to the bottom solid layer may be reduced. A protective film passing through the card could thus cause peeling problems for the bottom solid layer.

With reference to Figures 11 and 12A to 12E, a third implementation
15 mode of the electronic card manufacturing method according to the present invention will be described below. This implementation is particularly suited to automated production and provides cards of very high quality, without any risk of the protective film peeling off.

Protective film 76 is made for several batch manufactured cards, in
20 the form of a plate from which the cards are then cut out. This film 76 has apertures 32A for the electrical connections 64, of electronic assemblies or devices 40C incorporated in the cards, to pass through, and preferably apertures 78 in the zones provided for the second electronic units 10C. Each aperture 32A has four flaps 80a to 80d defined by four slits 82
25 provided in the corners of said aperture 32A. It will be noted that the protective film is very thin here.

In a first step of the card production method, film 76 is assembled by lamination, preferably hot lamination, with a solid layer 8 having apertures 6 for receiving respectively the first units 4 of the prefabricated electronic
30 assemblies or devices 40C. This solid layer and the protective film thus

adhere securely to each other. Apertures 32A are centred on apertures 6. Flaps 80a - 80d are then located along the perimeter of each aperture 6 in the general plane of protective film 76. It will be noted that the slits can be made after the lamination step, particular in the case of hot lamination.

5 Next, the electronic devices 40C are placed on the structure formed of bottom layer 8 and protective film 76 (Figure 12A) and the first units 4 are pushed into apertures 6 by folding flaps 80a - 80d against the lateral wall 30 of said apertures (Figure 12B). Units 4 are lowered sufficiently to release said flaps which then move at least partially back up towards the general
10 plane of film 76 (Figure 12C). Finally, units 4 are moved up inside apertures 6 to the level anticipated for the finished cards (Figure 12D). The flaps are then abutting against the lateral surface of unit 4. To close the slit securely between unit 4 and wall 30 of aperture 6 in which it is inserted, the ends of the flaps are preferably folded against the outer edge of the rear
15 face of unit 4 (Figure 12E). These folded ends are preferably bonded against said rear face. Again slits 82 may have almost zero width. Thus when the resin is subsequently deposited on film 76, electronic units 10C and their respective electrical connections 64 to units 4, the resin will not flow along walls 30 of windows 6. The subsequent steps are similar to those
20 of the other implementations modes of the method, as are the variants that can be envisaged for these subsequent steps. They will not be described again in detail here.

 In a variant that is not shown, the first electronic unit has a narrowed portion in the internal part thereof, this narrowed portion defining, on the top
25 internal surface of solid layer 8, a horizontal peripheral surface of said first unit substantially in the plane of said top internal surface while the height of the first first unit can be considerably greater than the thickness of the solid layer. When the first unit is moved up into its final position, the flaps of the protective film are then located on said peripheral surface of said first unit in
30 a horizontal position. The slits in the corners of the aperture can thus be properly closed since the flaps are located in the general plane of the

protective film; which guarantees a high level of sealing when the filler material passes in its non solid state, in particular a resin in a viscous liquid state.

5 It will be noted that, in the variant shown in Figure 12A, the bottom surface of internal unit 10C has bumps or raised portions which leave a space free between the internal unit and the top surface of layer 8 so as to allow the resin to fill this space when an internal layer of the cards is being formed and thus form a resin film that securely fixes unit 10C to layer 8.

CLAIMS

1. Method of manufacturing electronic cards each including at least a first electronic unit (4; 4A) at least partially arranged in a window (6; 6A) in a solid layer (8; 8A) of the card, and a second electronic unit (10; 10A; 10B) electrically connected to the first electronic unit, this method
5 including the following series of steps:

A) forming an electronic device or assembly (40; 40A; 40B) by making an electrical connection (18; 64; 64A) at least between said first electronic unit and said second electronic unit;

10 B) providing a first solid layer (8; 8A) having at least one window (6; 6A) for at least partially receiving the first electronic unit and providing said electronic device or assembly with the first electronic unit placed in said window;

C) providing a protective film formed of several parts (24, 26)
15 having respective profiles which, when assembled, define an aperture (32) into which said electrical connection passes, said aperture having smaller dimensions than those of the first electronic unit, or formed of a single part (50; 54) having at least one slit (52; 56a to 56d) starting from an aperture (32) made in said part, the dimensions of said aperture being smaller than
20 those of the first electronic unit, and placing said protective film such that it covers the first solid layer in a zone peripheral to said window and at least a lateral surface and/or the outer edge of a rear face of the first electronic unit to close any slit between the lateral wall (30) of the window and said first electronic unit;

25 D) at least on the protective film, providing a filler material (42) that is at least partially in a non solid phase when a card layer is being formed at least partially by said filler material, said material at least partially covering said electrical connection of said electronic device or assembly.

2. Method of manufacturing electronic cards each including at least a first electronic unit (4; 4A) at least partially arranged in a window (6; 6A) in a solid layer (8; 8A) of the card, and a second electronic unit (10; 10A; 10B) electrically connected to the first electronic unit, this method
5 including the following series of steps:

A) forming an electronic device or assembly (40; 40A; 40B) by making an electrical connection (18; 64; 64A) at least between said first electronic unit and said second electronic unit, providing a protective film having or arranged to define an aperture (32) whose dimensions are smaller
10 than those of the first electronic unit, and arranging the protective film between said first and second units with said electrical connection passing through said aperture;

B) providing a first solid layer (8; 8A) having at least one window (6; 6A) for at least partially receiving the first electronic unit, providing said
15 pre-assembled electronic device or assembly with said protective film and placing the first electronic unit in said window and said protective film partially on said first solid layer at the periphery of said window and, if not previously performed, partially against the lateral surface and/or the outer edge (5) of a rear face of the first electronic unit, so as to close any slit
20 between the lateral wall of the window and said first electronic unit;

C) at least on the protective film, providing a filler material (42) that is at least partially in a non solid phase when a card layer is being formed at least partially by said filler material, said material at least partially covering said electrical connection of said electronic device.

25 3. Electronic card manufacturing method according to claim 2, characterized in that said protective film is formed of several parts (24, 26), having respective profiles provided to define, when assembled, an aperture (32) into which said electrical connection passes and having smaller dimensions than those of the first electronic unit, or formed of a
30 single part (50; 54) having at least one slit starting from an aperture (32)

made in said part and having smaller dimensions than those of the first electronic unit.

4. Electronic card manufacturing method according to claim 1, characterized in that said protective film (50) has the general shape of a slit
5 ring.

5. Electronic card manufacturing method according to claim 1, characterized in that said protective film is formed of two parts (24; 26) at least one of which is generally U-shaped or both parts are L-shaped.

6. Method of manufacturing electronic cards, each card including
10 at least a first electronic unit (4) at least partially arranged in a window (6) in a solid layer (8) of the card, and a second electronic unit (10C) electrically connected to the first electronic unit, this method including a first group of the following steps:

A) forming an electronic device or assembly (40C) by making an
15 electrical connection (64) at least between said first electronic unit and said second electronic unit;

B) forming a structure including a protective film (76) with at least one aperture (32) that has smaller dimensions than those of the first electronic unit and has flaps (80a to 80d) at the periphery thereof, and a first
20 solid layer (8) having at least one window (6) for at least partially receiving the first electronic unit, said protective film being assembled to said first solid layer with said at least one aperture centred on said at least one window;

this first group of steps being followed by the second series of steps:

25 C) providing said structure and said electronic device or assembly to a card production equipment or facility and placing the first electronic unit opposite said aperture, then pushing said first unit into said window by folding said flaps in the direction of the lateral wall of the aperture until the flaps are released and then move back up at least partially towards the
30 general plane of the protective film;

D) the first unit is moved back up towards said aperture so that said flaps are applied against the lateral surface and/or a rear face of said first unit so as to close any slit between the lateral wall of the window and the first unit, said electrical connection passing through said aperture;

5 E) at least on the protective film, providing a filler material that is at least partially in a non solid phase when a card layer is being formed at least partially by said filler material, said material at least partially covering said electrical connection of said electronic device.

7. Electronic card manufacturing method according to claim 6,
10 characterized in that said protective film and said first solid layer are laminated together.

8. Electronic card manufacturing method according to claim 6,
characterized in that said protective film initially has a plurality of apertures respectively centred on a plurality of windows in the solid layer to which said
15 protective film is assembled, said structure being provided for forming a batch of cards each incorporating an electronic device or assembly.

9. Electronic card manufacturing method according to claim 1,
characterized in that a first part (42A) of the filler material is formed by a resin provided underneath the second electronic unit while the latter is
20 raised relative to the first solid layer or turned onto the top side thereof, a second part of the filler material being then provided on said second electronic unit which is folded down or turned onto the bottom side thereof so as to be located on said first part of said filler material.

10. Electronic card manufacturing method according to claim 1,
25 characterized in that the filler material is formed by at least one resin, said resin being spread out using a roller or blade or introduced laterally, the second electronic unit being arranged such that a part of said resin penetrates underneath said second unit when said layer is being formed at least partially by said filler material.

11. Electronic card manufacturing method according to claim 1, characterized in that a resin layer (60) is initially deposited on the bottom surface of a support (12) of the second electronic unit.

12. Electronic card manufacturing method according to claim 1,
5 characterized in that a second solid layer (44) is provided on said filler material before pressure is applied thereto.

13. Electronic card manufacturing method according to claim 1, characterized in that said protective film has an adhesive or heat reactivatable surface (62) which, once applied against a rear face of the first
10 electronic unit, adheres thereto.

14. Electronic card manufacturing method according to claim 1, characterized in that said protective film has limited dimensions, such that said protective film does not extend underneath most of the second electronic unit.

15. Electronic card manufacturing method according to claim 3, characterized in that said protective film (50) has the general shape of a slit ring.

16. Electronic card manufacturing method according to claim 3, characterized in that said protective film is formed of two parts (24; 26) at
20 least one of which is generally U-shaped or both parts are L-shaped.

17. Electronic card manufacturing method according to claim 2, characterized in that a first part (42A) of the filler material is formed by a resin provided underneath the second electronic unit while the latter is raised relative to the first solid layer or turned onto the top side thereof, a
25 second part of the filler material being then provided on said second electronic unit which is folded down or turned onto the bottom side thereof so as to be located on said first part of said filler material.

18. Electronic card manufacturing method according to claim 6, characterized in that a first part (42A) of the filler material is formed by a

resin provided underneath the second electronic unit while the latter is raised relative to the first solid layer or turned onto the top side thereof, a second part of the filler material being then provided on said second electronic unit which is folded down or turned onto the bottom side thereof
5 so as to be located on said first part of said filler material.

19. Electronic card manufacturing method according to claim 2, characterized in that the filler material is formed by at least one resin, said resin being spread out using a roller or blade or introduced laterally, the second electronic unit being arranged such that a part of said resin
10 penetrates underneath said second unit when said layer is being formed at least partially by said filler material.

20. Electronic card manufacturing method according to claim 6, characterized in that the filler material is formed by at least one resin, said resin being spread out using a roller or blade or introduced laterally, the
15 second electronic unit being arranged such that a part of said resin penetrates underneath said second unit when said layer is being formed at least partially by said filler material.

21. Electronic card manufacturing method according to claim 2, characterized in that a resin layer (60) is initially deposited on the bottom
20 surface of a support (12) of the second electronic unit.

22. Electronic card manufacturing method according to claim 6, characterized in that a resin layer (60) is initially deposited on the bottom surface of a support (12) of the second electronic unit.

23. Electronic card manufacturing method according to claim 2, characterized in that a second solid layer (44) is provided on said filler
25 material before pressure is applied thereto.

24. Electronic card manufacturing method according to claim 6, characterized in that a second solid layer (44) is provided on said filler material before pressure is applied thereto.

25. Electronic card manufacturing method according to claim 2, characterized in that said protective film has an adhesive or heat reactivatable surface (62) which, once applied against a rear face of the first electronic unit, adheres thereto.

5 26. Electronic card manufacturing method according to claim 6, characterized in that said protective film has an adhesive or heat reactivatable surface (62) which, once applied against a rear face of the first electronic unit, adheres thereto.

27. Electronic card manufacturing method according to claim 2,
10 characterized in that said protective film has limited dimensions, such that said protective film does not extend underneath most of the second electronic unit.

28. Electronic card manufacturing method according to claim 6,
15 characterized in that said protective film has limited dimensions, such that said protective film does not extend underneath most of the second electronic unit.